



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Material Declaration Champions
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A30X*V772BAJ	A	CA2A	2015-07-30
Amount	UoM	Unit type	ST ECOPACK Grade	
190.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	8X8X0.9	56	No lead	
Comment	Package: VFQFPN 8X8X0.9 56L PITCH 0.50; MD valid for STA311B - STA311BTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A30X*V772BAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	5.846	mg	supplier	die	Silicon (Si)	7440-21-3		5.524	mg	944920	29074
				supplier	metallization	Aluminium (Al)	7429-90-5		0.055	mg	9408	289
				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	171	5
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	171	5
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	2224	68
				supplier	metallization	Tungsten (W)	7440-33-7		0.013	mg	2224	68
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	1882	58
				supplier	Passivation	Silicon Oxide	7631-86-9		0.114	mg	19501	600
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.114	mg	19501	600
				Leadframe	Copper & Its alloys	50.361	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						1.151	mg	22855	6058
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.069	mg	1370	363
supplier	alloy	Zinc (Zn)	7440-66-6						0.060	mg	1191	316
supplier	metallization	Nickel (Ni)	7440-02-0						0.143	mg	2839	753
supplier	metallization	Palladium (Pd)	7440-05-3						0.009	mg	179	47
supplier	metallization	Gold (Au)	7440-57-5						0.004	mg	79	21
supplier	glue or tape (choose)	Silver (Ag)	7440-22-4						1.246	mg	683864	6558
Die attach	Other inorganic materials	1.822	mg	supplier	glue or tape	methylene diacrylate	42594-17-2		0.455	mg	249726	2395
				supplier	glue or tape	Dicyclopentenloxyethyl methacrylate	68586-19-6		0.055	mg	30187	289
				supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.055	mg	30187	289
				supplier	glue or tape	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.009	mg	4940	47
				supplier	glue or tape	Palladium (Pd)	7440-05-3		0.002	mg	1098	11
				supplier	wire	Copper (Cu)	7440-50-8		0.942	mg	1000000	4958
Bonding wires	Precious Metals	0.942	mg	supplier	wire	Copper (Cu)	7440-50-8		0.942	mg	1000000	4958
				supplier	mold compound	silica vitreous	60676-86-0		115.306	mg	880004	606874
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		6.551	mg	49997	34479
				supplier	mold compound	Phenolic resin	205830-20-2		5.110	mg	38999	26895
				supplier	mold compound	Epoxy resin	Proprietary		2.621	mg	20003	13795
				supplier	mold compound	carbon black	1333-86-4		0.262	mg	2000	1379
Encapsulation	Other Organic Materials	131.029	mg	supplier	mold compound	other	Proprietary		1.179	mg	8998	6205